

Università degli Studi di Padova – Dipartimento di Ingegneria Industriale

Corso di Laurea in Ingegneria Chimica e dei Materiali

***Relazione per la prova finale***  
***«Thin Pure Plate Lead: Technology and Patent Analysis»***

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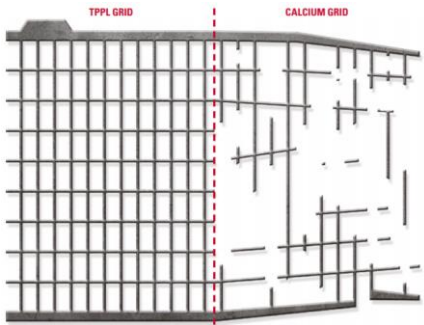
Laureando: *Samuele Manauzzi*

Padova, 13/09/2024

TPPL = Thin Pure Plate Lead

Lead purity affects

- Corrosion: reduced → thin plates + prolonged battery lifetime
- Recharge capability: larger reactive surface (more plates) → faster recharge
- Gas generation: inhibited electrolysis → no dry-out and water topping up



Advantages

Reduced corrosion

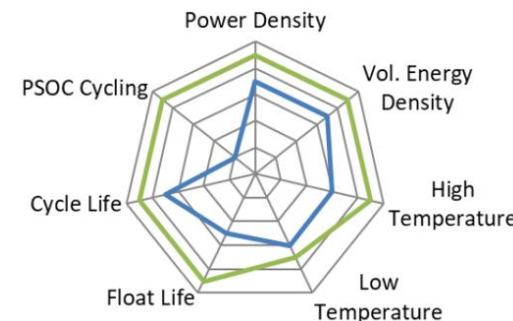
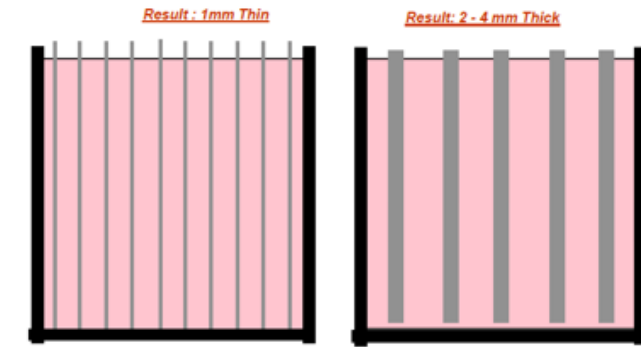
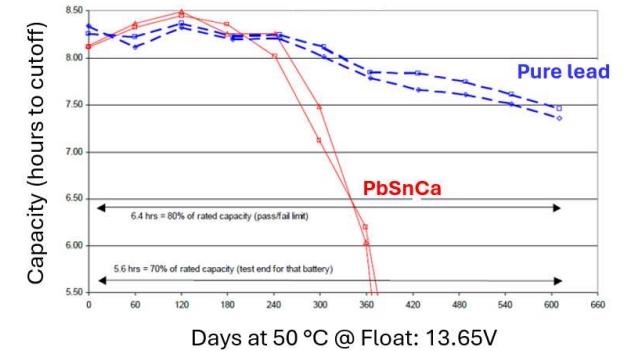
- Higher lifetime
- High temperature resistance
- High energy density
- High power

Lower self-discharge

- Higher shelf life
- Reduced dry-out
- High safety → no gassing

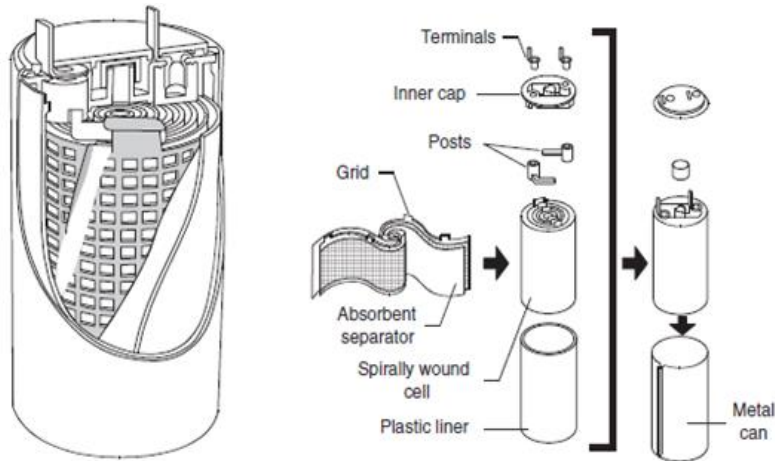
Drawbacks

- Low mechanical stability → grid growth and deformation
- Shedding
- Creep
- Intergranular corrosion



— PbSnCa batteries  
— TPPL batteries

- How can we enhance TPPL grid resistance to corrosion?



Tin content

Grains size



Technology  
study



Corrosive attack  
mechanism

Affected by  
cristallography and alloy  
composition



- How can we solve problems related  
to TPPL technology itself?



Patent  
analysis

Grid pattern

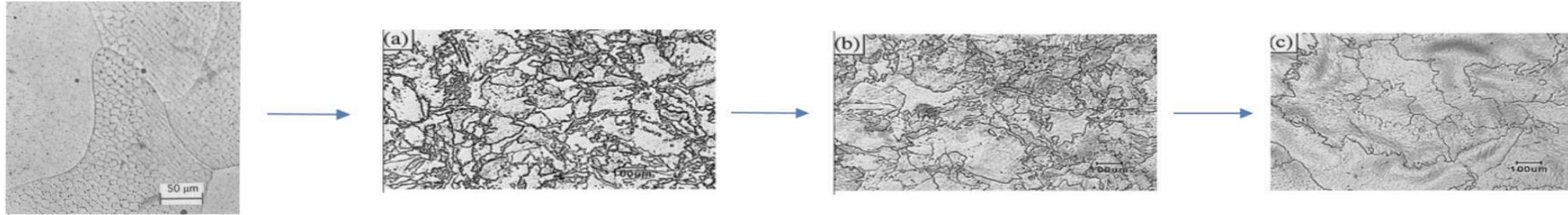
Post treatments

Optimized casting parameters

For this purpose → Fiamm grid based on TPPL technology was compared with 2 other grids, with the same technology, from competitors.

- Intergranular matrix → eutectic mixture with lamellar morphology → Volta's effect → grain boundaries subjected to corrosion
- Higher tin content → larger grains

Element	FIAMM grid	Competitor 1	Competitor 2
Sn (%)	< 1	≈ 0	≈ 0
Other elements in traces			

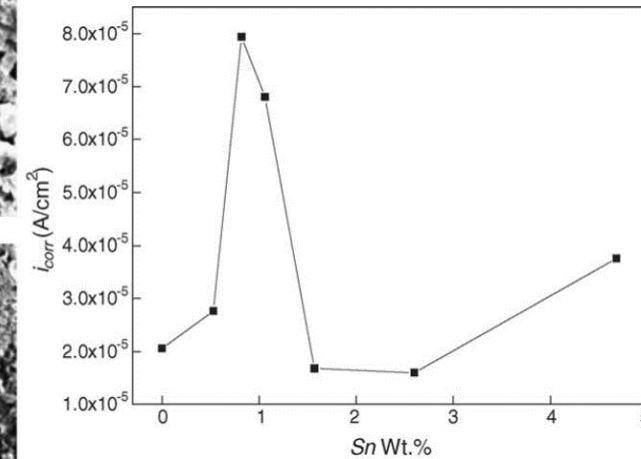
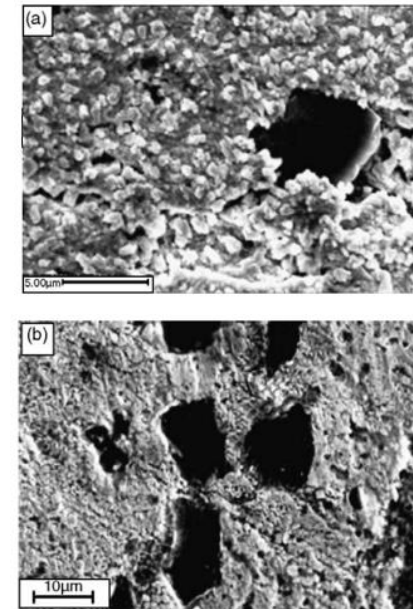


From left to right:  
Pure lead, 0.3% Sn,  
0.6% Sn, 1.0% Sn

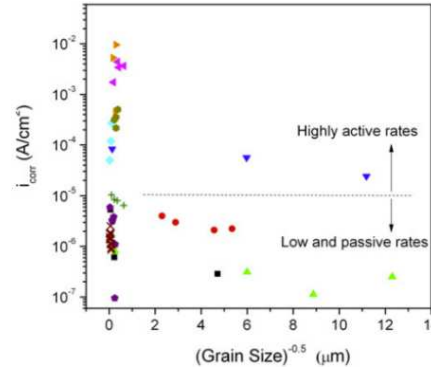
- Tin content affects ion and electron transportation through passivation layer → determine corrosion rate

## PASSIVATION LAYER (P.L.):

- Formation between grid and PAM, made of Pb and Sn oxides
- Sn < 0.8% wt.: pitting (mesoporous Sn(II)) + conductive  $PbO_x (1 < x < 2)$
- 0.8% < Sn < 2.6% wt.: stable  $SnO_2$  + conductive  $PbO_x (1 < x < 2)$
- Sn > 2.6% wt.: excessive Sn segregated → severe intergranular corrosion



Effect of grains size → varies whether the metal passivate or not: if a P.L. is formed or not → depends on electrode-electrolyte couple

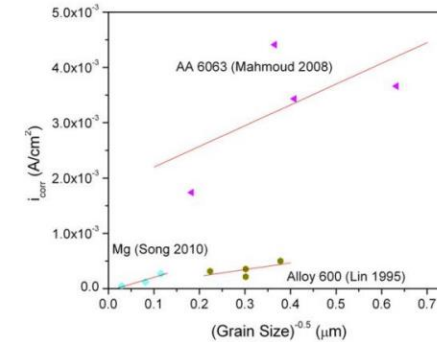
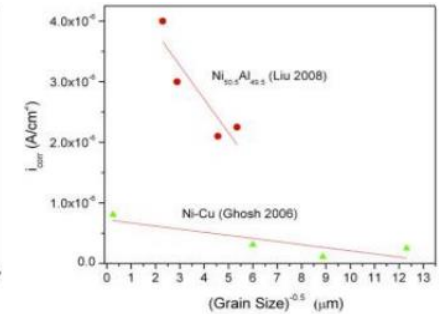
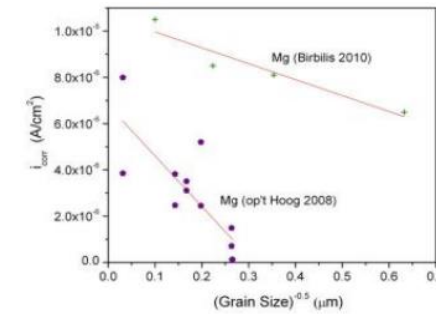


	FIAMM grid	Competitor 1	Competitor 2
Average diam.	26.92	20.50	36.99
Average perim.	84.57*	64.40*	116.2*
*Calculated considering a circular section			

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Couple with

- Low corrosion rates / P.L. formed → corrosion rates decrease with grains size reduction →
- High rate of corrosion / P.L. not formed → corrosion rates increase with grains size reduction →



P.L. is formed for the couple:  $Pb + H_2SO_4 \rightarrow$  fine grain array is preferable → more corrosion resistant

To obtain a fine grain array → suggested fast cooling rate of 0.8-1.5 °C/s

	FIAMM grid	Competitor 1	Competitor 2
<b>Weight loss</b>	3	1	2
<b>Corrosion rate</b>	3	1	2
<b>Sn (%)</b>	< 1	≈ 0	≈ 0
<b>Average perim. (μm)</b>	84,57	64,4	116,19

Legend: best performance = 1; worst performance = 3

Best configuration in terms of corrosion resistance: Competitor 1

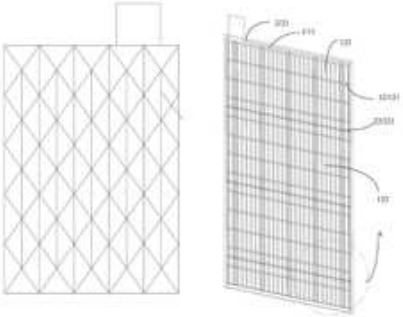
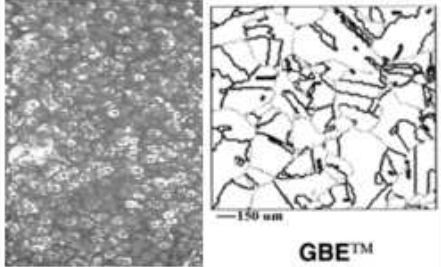
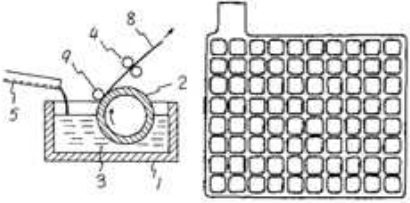
- very low tin content → no pitting and low conductivity
- fine grain array → inhibited corrosion thanks to P.L. presence

Grid's tin content vs. corrosion resistance:

- Fiamm grid: highest Sn concentration →  
→ worst corrosion resistance → highest weight loss and corrosion rate
- Competitor grids: similar Sn content →  
→ other parameters affect grid corrosion

Grid's grain size vs. corrosion resistance:

- Competitor grid 1: fine grain array →  
→ best corrosion resistance → lowest weight loss and corrosion rate
- Competitor grid 2: coarse grain array →  
→ weight loss and corrosion rate slightly higher than Competitor grid 1

PROBLEM	SOLUTION	DRAWINGS	PATENT	APPLICANT
Corrosion Shedding Deformation	<p><u>Grid pattern:</u> The cross-section of the hole is a triangular structure Reinforcing polymeric frame and ribs</p>		<p>CN215955327U CN211957792U</p>	<p>HOPPECKE CAMEL</p>
Shedding Corrosion	<p><u>Post treatment:</u> Recrystallization is obtained by deformation and annealing Sandblasting improves active mass adhesion</p>		<p>CA2468022A1 CN109065890A</p>	<p>INTEGRAN TECHNOLOGIES  JIANGSU HUAFU STORAGE NEW TECH</p>
Quality casting (no reference to alloy composition)	<p>Casting wheel with a concave groove on the peripheral surface. The molten lead is continuously solidified in the concave groove. Casting speed is about 300 mm/s, diameter of the rotating wheel is 250 mm and thickness of the lead lattice is 3 mm.</p>		<p>JPH0665035B2 JPS6012668A</p>	<p>HITACHI</p>

- **DESIGN FEATURES:**

- Sn as close as possible to 0% wt.
  - The ribs mesh is triangular
  - Reinforcing polymeric frame and ribs
- } to prevent grid deformation and shedding

- **CASTING PARAMETERS:**

- Fast cooling rate to obtain fine grain arrays: 0.8-1.5 °C/s
- Casting speed: 300 mm/s ( $\phi_{\text{wheel}} = 250$  mm; thickness<sub>grid</sub> = 3 mm )

- **POST TREATMENT:**

- Mechanical deformation among 40-95°C
  - Annealing between 150 and 330°C ( $T_m$ )
- } to ensure recrystallization
- Sandblasting to improve active mass adhesion and prevent shedding





Company subject to the management and coordination of Resonac Corporation